Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

VICROCHIP Semiconductor Device	(Q2X) 028 PDIP .600in Matte Tin	Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				JEDEC 97 Product Marking and/or Pkg. Labeling e3	
		"Contained In"	% Total			3226.93	(mg) Total	Mold Compound	% ot Total Weight	79.35
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	3220.33		·		75.55
Fused Silica Metal Hydro Oxide	60676-86-0 Trade Secret	Mold Compound Mold Compound	57.132 8.729	2323.387 354.962	571,320 87,285		Fused Silica Metal Hydro Oxide	60676-86-0 Trade Secret	72.00 11.00	
Epoxy Resin	Trade Secret	Mold Compound	5.555	225.885	55,545		Epoxy Resin	Trade Secret	7.00	
Phenol Resin	Trade Secret	Mold Compound	5.555	225.885	55,545		Phenol Resin	Trade Secret	7.00	
SiO2	14808-60-7	Mold Compound	1.984	80.673	19,838	1	SiO2	14808-60-7	2.50	
Carbon Black	1333-86-4	Mold Compound	0.397	16.135	3,968		Carbon Black	1333-86-4	0.50	
Copper	7440-50-8	Lead Frame Tape	9.984	406.006	99,837			Total	100.00	
Iron	7439-89-6	Lead Frame Tape	0.246	9.987	2,456	424.97	(mg) Total	Lead Frame	% of Total Weight	10.45
Silver	7440-22-4	Lead Frame Tape	0.199	8.096	1,991		Copper	7440-50-8	95.54	
Zinc Phosphorous	7440-66-6 7723-14-0	Lead Frame Tape Lead Frame Tape	0.013	0.531 0.351	131 86		Iron Silver	7439-89-6 7440-22-4	2.35 1.91	
Polyimide	25038-81-7	Lead Frame Tape	0.009	8.743	2,150		Zinc	7440-22-4 7440-66-6	0.13	
Poly - ethylene – terephthalate	25038-59-9	Lead Frame Tape	0.190	7.727	1.900		Phosphorous	7723-14-0	0.13	
NBR	9003-18-3	Lead Frame Tape	0.035	1.423	350	ļ.	1 Hospilorous	Total	100.00	
Bismaleimide	79922-55-7	Lead Frame Tape	0.030	1.220	300	20.33	(mg) Total	Lead Frame Tape	% of Total Weight	0.5
Phenol resin	453-20-5 / 9016-8	Lead Frame Tape	0.030	1,220	300	20.00	Polyimide	25038-81-7	43.00	0.0
Silver	7440-22-4	Die Attach	0.550	22.375	5,502	Pol	/ - ethylene – terephthalate	25038-59-9	38.00	
Epoxy Resin	9003-36-5	Die Attach	0.110	4,474	1.100		NBR	9003-18-3	7.00	
Diluent	3101-60-8	Die Attach	0.055	2.236	550		Bismaleimide	79922-55-7	6.00	
Phenolic hardener	Trade secret	Die Attach	0.022	0.894	220		Phenol resin	28453-20-5 / 9016-83-5	6.00	
Amine type hardener	827-43-0	Die Attach	0.011	0.448	110	1		Total	100.00	
Dicyandiamide	461-58-5	Die Attach	0.002	0.073	18	30.50	(mg) Total	Die Attach	% of Total Weight	0.75
Silicon	7440-21-3	Chip (Die)	7.500	305.003	75,000		Silver	7440-22-4	73.36	
Copper	7440-50-8	Wire Bond palladium coated copper (CuPd)	0.197	7.991	1,965		Epoxy Resin	9003-36-5	14.67	
Palladium	7440-05-3	Wire Bond palladium coated copper (CuPd)	0.004	0.142	35		Diluent	3101-60-8	7.33	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	50.834	12,500		Phenolic hardener	Trade secret	2.93	
		TOTALS:	100.000	4,066.700	1,000,000		Amine type hardener	827-43-0	1.47	
		g Total Mass					Dicyandiamide	461-58-5 Total	0.24	
i) and 2002/53/EC (End-of-Life Vehicles (ELV) without ex		2002/95/EC (27 January 2003) & Directive 2011/65/EU (08	June 2011) ar							
				20.0/000/20	(31 March				100.00	
pliance with the above EU Directives has been verified	via internal design controls	s, supplier declarations, and /or analytical test data.		2010/000/20	(ST Waren	305.00	Total (mg)	Chip (Die)	% of Total Weight	7.5
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